

Chun-Hao Chen

List of Publications by Year in descending order

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#	ARTICLE	IF	CITATIONS
1	Intermetallic Growth at the Interfaces Between Zn ₄ Sb ₃ Thermoelectric Material and Various Metallic Electrodes. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2022, 53, 136.	2.2	0
2	Microstructure evolution and failure mechanism of electromigration in Ag-alloy bonding wire. Journal of Alloys and Compounds, 2022, 913, 165266.	5.5	7
3	Interfacial Reactions of Ag and Ag-4Pd Stud Bumps with Sn-3Ag-0.5Cu Solder for Flip Chip Packaging. Journal of Electronic Materials, 2021, 50, 249-257.	2.2	1
4	Grain growth and twin formation in a Ag-4Pd alloy ribbon after annealing treatments. Journal of Alloys and Compounds, 2021, 863, 158619.	5.5	8
5	Effects of Grain Size on the Ag Dissolution and Ion Migration of Ag-4Pd Alloy Wires. Journal of Electronic Materials, 2021, 50, 5955-5964.	2.2	3
6	Interfacial reactions in Zn ₄ Sb ₃ /titanium diffusion couples. Journal of Alloys and Compounds, 2021, 881, 160630.	5.5	1
7	Effect of Post-Weld Heat Treatment on the Solid-State Diffusion Bonding of 6061 Aluminum Alloy. Applied Sciences (Switzerland), 2021, 11, 9660.	2.5	9
8	Ultrasonic Bonding of Ag and Ag-Alloy Ribbon—An Innovative Alternative for High Power IC Packages. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1061-1068.	2.5	7
9	Improvement of Sn-3Ag-0.5Cu Soldered Joints Between Bi _{0.5} Sb _{1.5} Te ₃ Thermoelectric Material and a Cu Electrode. Journal of Electronic Materials, 2020, 49, 3391-3399.	2.2	7
10	Intermetallic Compounds at the Interfaces of Ag-Pd Alloy Stud Bumps With Al Pads. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1657-1665.	2.5	7
11	Evaluation of Corrosion Resistance of Ag-Alloy Bonding Wires for Electronic Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 146-153.	2.5	12
12	Electrolytic Migration of Ag-Pd Alloy Wires with Various Pd Contents. Journal of Electronic Materials, 2018, 47, 3634-3638.	2.2	5
13	Mechanism of the Electromigration in Ag-Pd Alloy Bonding Wires. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2018, 49, 5904-5910.	2.2	9
14	Applications of Ag-alloy stud bump for IC and LED packages. , 2014, , .		0